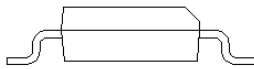
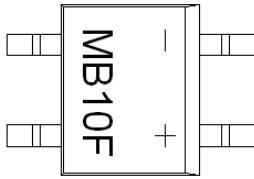


**MBF**

**Features**

- Glass Passivated Die Construction
- High Forward surge capability
- Low Forward Voltage Drop
- High temperature soldering guaranteed: 260°C/10 S
- Lead and body according with RoHS standard

**Mechanical Data**

- MBF small outline plastic package
- As Marked on Case
- Epoxy UL: 94V-0
- Mounting Position: Any

**Maximum Ratings & Thermal Characteristics**

(Ratings at 25°C ambient temperature unless otherwise specified.)

Parameters	Symbol	MB05F	MB1F	MB2F	MB4F	MB6F	MB8F	MB10F	Unit
Maximum repetitive peak reverse voltage	VRRM	50	100	200	400	600	800	1000	V
Maximum RMS voltage	VRMS	35	70	140	280	420	560	700	V
Maximum DC blocking voltage	VDC	50	100	200	400	600	800	1000	V
Average Rectified Output Current @Ta=40°C Note 1	I <sub>o</sub>	0.5							A
Average Rectified Output Current @Ta=40°C Note 2		0.8							
Non-repetitive Peak forward surge current 8.3 ms single half sine-wave (JEDEC Method)	IFSM	30							A
I <sup>2</sup> t Rating for Fusing(t<8.3ms)	I <sup>2</sup> t	5.0							A <sup>2</sup> s
Typical thermal resistance	R <sub>θJA</sub>	60							°C/W
Operation junction and Storage temperature range	T <sub>j</sub> , T <sub>STG</sub>	-55-+150							°C

 Note: 1, Mounted on glass epoxy PC board with 1.3mm<sup>2</sup> solder pad;

 2, Mounted on aluminum substrate PC board with 1.3mm<sup>2</sup> solder pad.

**Electrical Characteristics**

(Ratings at 25°C ambient temperature unless otherwise specified).

参数 Parameters	符号 Symbol	MB05F	MB1F	MB2F	MB4F	MB6F	MB8F	MB10F	单位 Unit
最大正向电压 @IF=0.5A Max. forward voltage	VF	1.0							V
最大反向电流@VDC TA=25°C Max. reverse current TA=125°C	IR	5 500							uA
典型结电容 VR=4.0V, f=1MHz Type junction capacitance	C <sub>j</sub>	13							pF

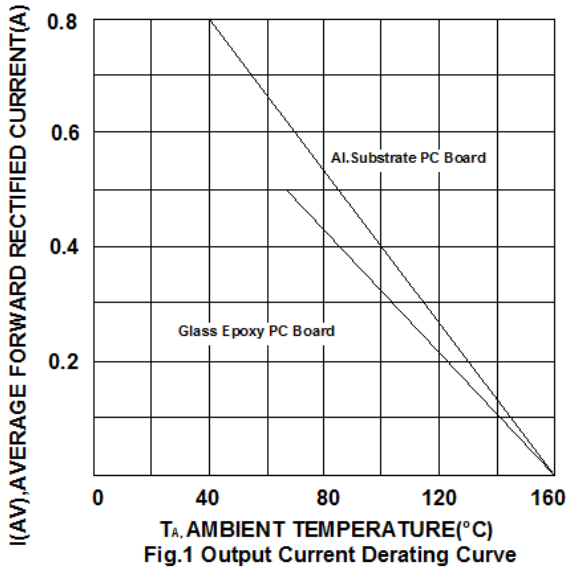


Fig.1 Output Current Derating Curve

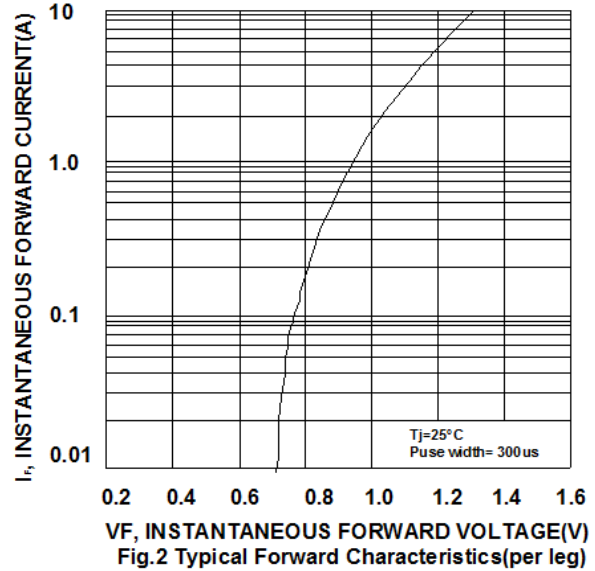


Fig.2 Typical Forward Characteristics(per leg)

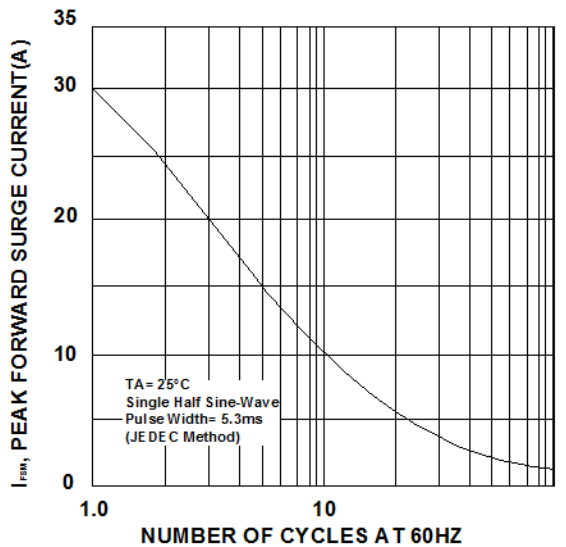


Fig.3 Maximum Peak Forward Surge Current (per leg)

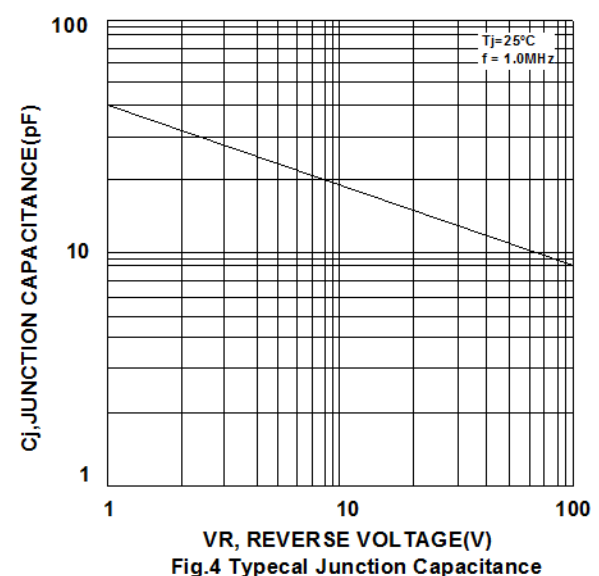


Fig.4 Typical Junction Capacitance

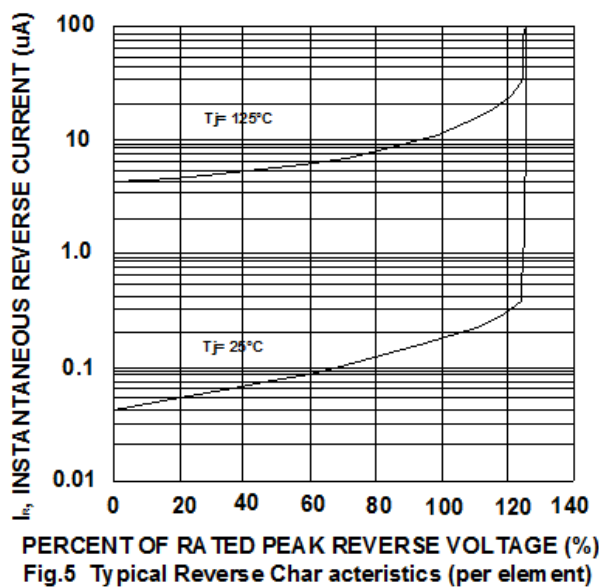
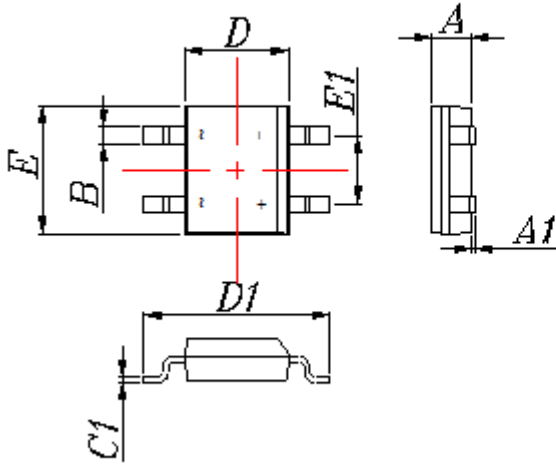


Fig.5 Typical Reverse Characteristics (per element)

**MBF PACKAGE OUTLINE**

Plastic surface mounted package

MBF



Symbol	Min.	Max.
A	1.30	1.50
A1	--	0.2
B	0.50	0.70
C1	0.15	0.30
D	3.70	3.90
D1	6.70	6.90
E	4.70	4.90
E1	2.45	2.55

单位: mm